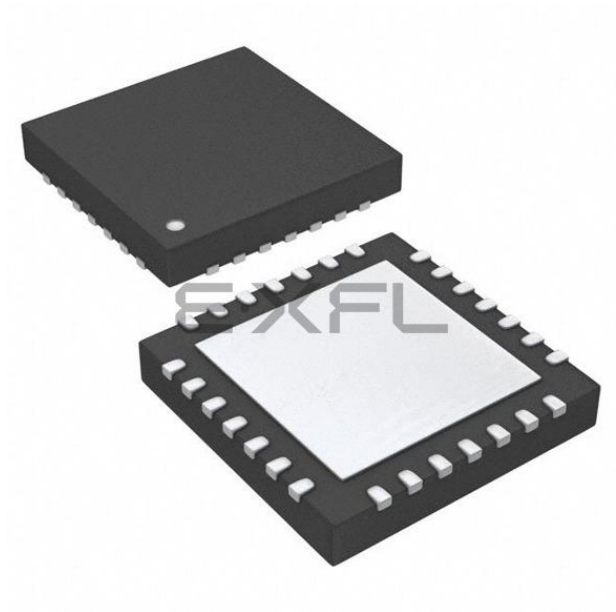

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 24x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f18855-i-mv

TABLE 1-3: PIC16F18875 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
VSS	VSS	Power	—	Ground reference.
OUT(2)	ADGRDA	—	CMOS/OD	ADC Guard Ring A output.
	ADGRDB	—	CMOS/OD	ADC Guard Ring B output.
	C1OUT	—	CMOS/OD	Comparator 1 output.
	C2OUT	—	CMOS/OD	Comparator 2 output.
	SDO1	—	CMOS/OD	MSSP1 SPI serial data output.
	SCK1	—	CMOS/OD	MSSP1 SPI serial clock output.
	SDO2	—	CMOS/OD	MSSP2 SPI serial data output.
	SCK2	—	CMOS/OD	MSSP2 SPI serial clock output.
	TX	—	CMOS/OD	EUSART Asynchronous mode transmitter data output.
	CK(3)	—	CMOS/OD	EUSART Synchronous mode clock output.
	DT(3)	—	CMOS/OD	EUSART Synchronous mode data output.
	DSM	—	CMOS/OD	Data Signal Modulator output.
	TMR0	—	CMOS/OD	Timer0 output.
	CCP1	—	CMOS/OD	Capture/Compare/PWM1 output (compare/PWM functions).
	CCP2	—	CMOS/OD	Capture/Compare/PWM2 output (compare/PWM functions).

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2CHV= High Voltage XTAL= Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 13-1 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 13-3.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

TABLE 3-13: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-31 (CONTINUED)

Address	Name	PIC16(L)F18855	PIC16(L)F18875	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
Bank 0 (Continued)													
01Bh	—	—	—	Unimplemented								-	-
01Ch	TMR0L			Holding Register for the Least Significant Byte of the 16-bit TMR0 Register								0000 0000	0000 0000
01Dh	TMR0H			Holding Register for the Most Significant Byte of the 16-bit TMR0 Register								1111 1111	1111 1111
01Eh	T0CON0			T0EN	—	T0OUT	T016BIT	T0OUTPS<3:0>				0-00 0000	0-00 0000
01Fh	T0CON1			T0CS<2:0>			T0ASYNC	T0CKPS<3:0>				0000 0000	0000 0000

Legend: x = unknown, u = unchanged, q =depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

Note 1: Register present on PIC16F18855/75 devices only.

2: Unimplemented, read as '1'.

TABLE 3-13: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-31 (CONTINUED)

Address	Name	PIC16(L)F18855	PIC16(L)F18875	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
Banks 15													
CPU CORE REGISTERS; see Table 3-2 for specifics													
78Ch	—	—		Unimplemented								—	—
78Dh	—	—		Unimplemented								—	—
78Eh	—	—		Unimplemented								—	—
78Fh	—	—		Unimplemented								—	—
790h	—	—		Unimplemented								—	—
791h	—	—		Unimplemented								—	—
792h	—	—		Unimplemented								—	—
793h	—	—		Unimplemented								—	—
794h	—	—		Unimplemented								—	—
795h	—	—		Unimplemented								—	—
796h	PMD0			SYSCMD	FVRMD	—	CRCMD	SCANMD	NVMMD	CLKRMD	IOCMD	00-0 0000	00-0 0000
797h	PMD1			NCOMD	TMR6MD	TMR5MD	TMR4MD	TMR3MD	TMR2MD	TMR1MD	TMR0MD	0000 0000	0000 0000
798h	PMD2			—	DACMD	ADCMD	—	—	CMP2MD	CMP1MD	ZCDMD	-00- -000	-00- -000
799h	PMD3			—	PWM7MD	PWM6MD	CCP5MD	CCP4MD	CCP3MD	CCP2MD	CCP1MD	-000 0000	-000 0000
79Ah	PMD4			—	UART1MD	MSSP2MD	MSSP1MD	—	CWG3MD	CWG2MD	CWG1MD	-000 -000	-000 -000
79Bh	PMD5			SMT2MD	SMT1MD	—	CLC4MD	CLC3MD	CLC2MD	CLC1MD	DSMMD	00-0 0000	00-0 0000
79Ch	—	—		Unimplemented								—	—
79Dh	—	—		Unimplemented								—	—
79Eh	—	—		Unimplemented								—	—
79Fh	—	—		Unimplemented								—	—

Legend: x = unknown, u = unchanged, q =depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

Note 1: Register present on PIC16F18855/75 devices only.

2: Unimplemented, read as '1'.

5.0 RESETS

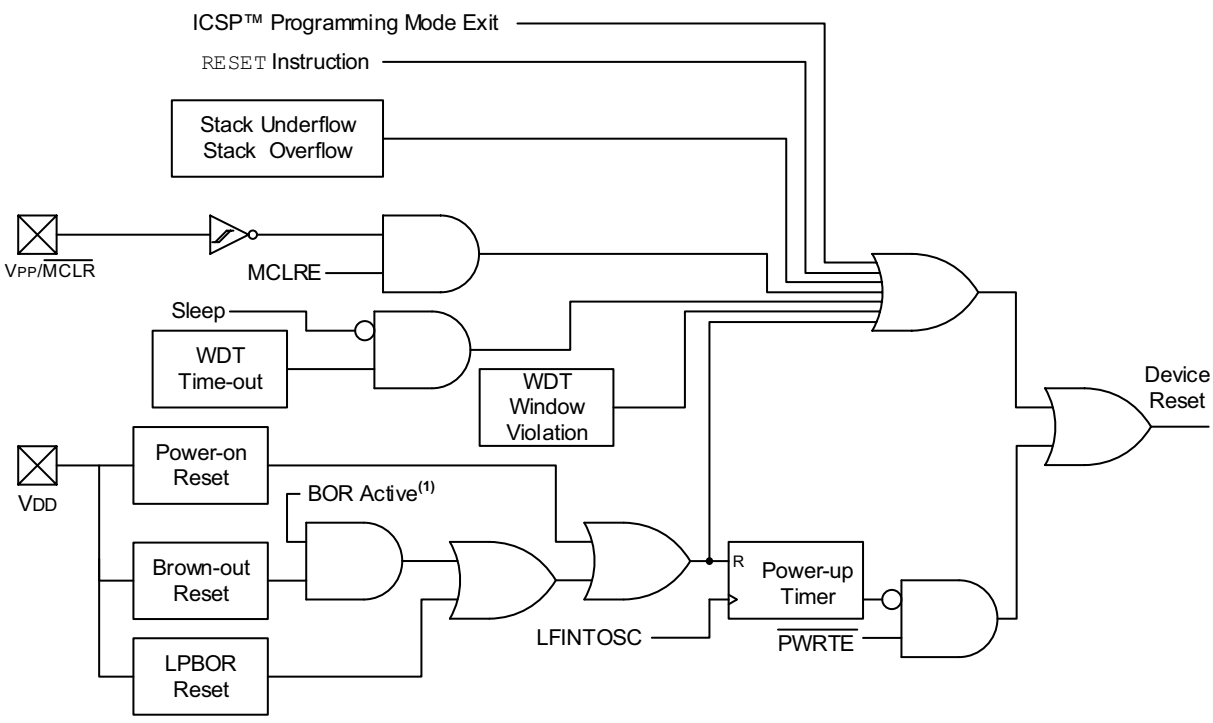
There are multiple ways to reset this device:

- Power-On Reset (POR)
- Brown-Out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional Power-up timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: See Table 5-1 for BOR active conditions.

10.4.8 WRITE VERIFY

It is considered good programming practice to verify that program memory writes agree with the intended value. Since program memory is stored as a full page then the stored program memory contents are compared with the intended data stored in RAM after the last write is complete.

FIGURE 10-8: FLASH PROGRAM MEMORY VERIFY FLOWCHART

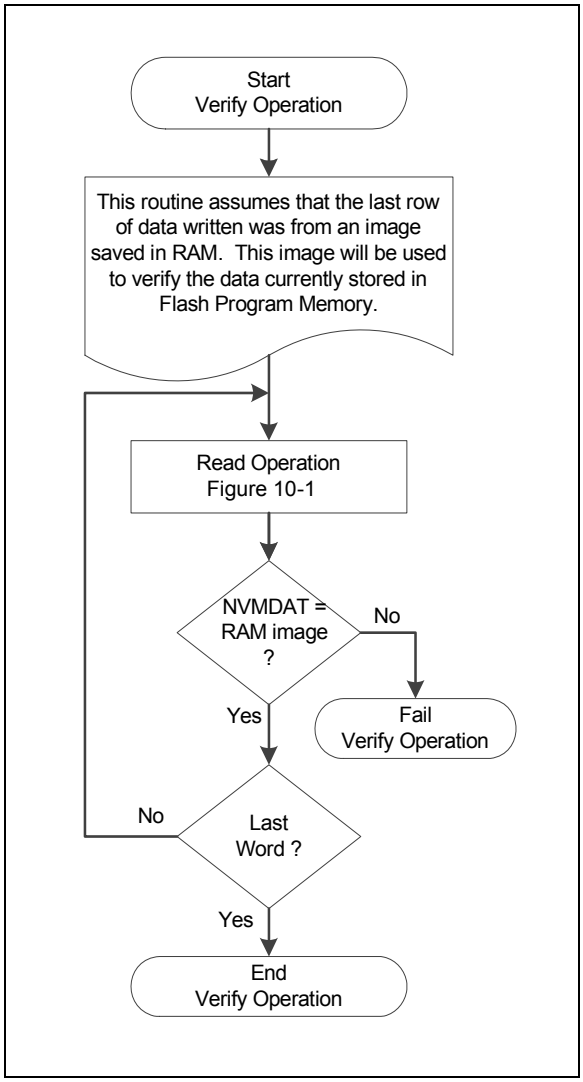
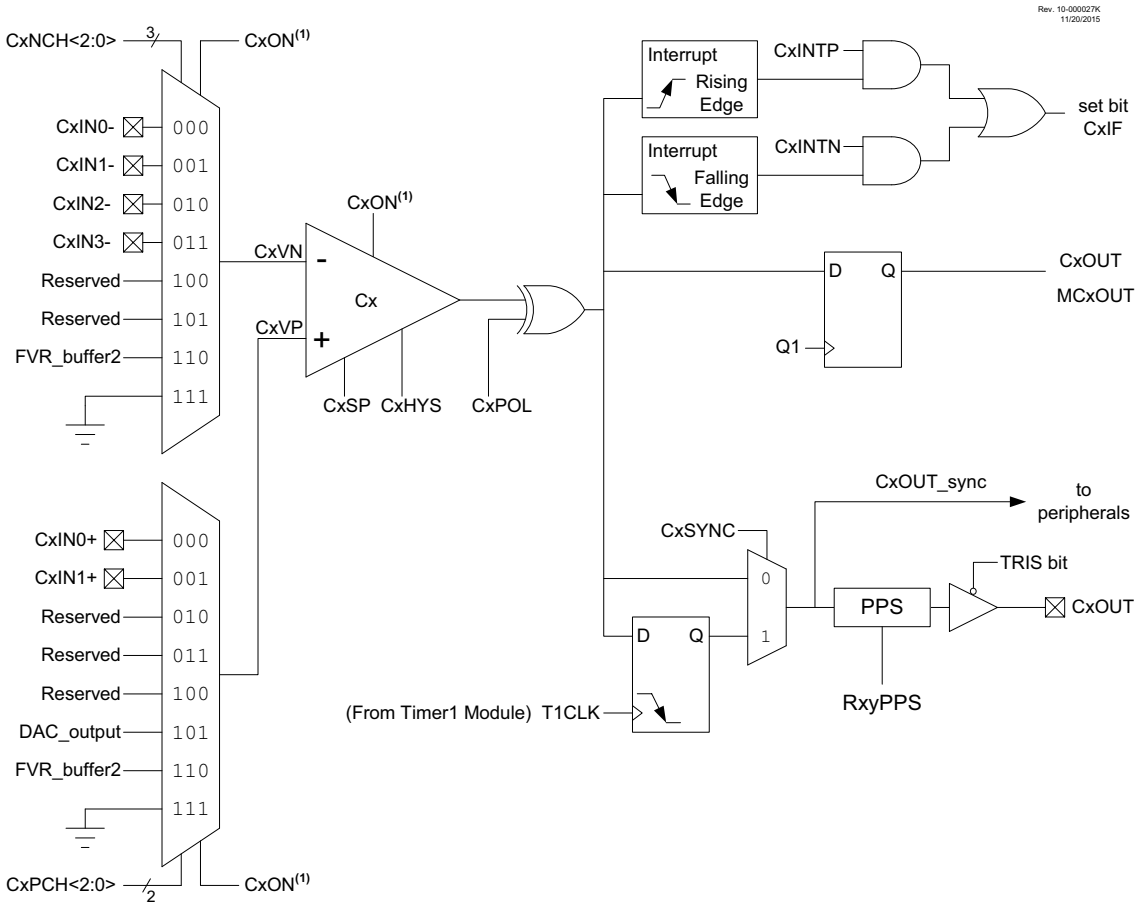
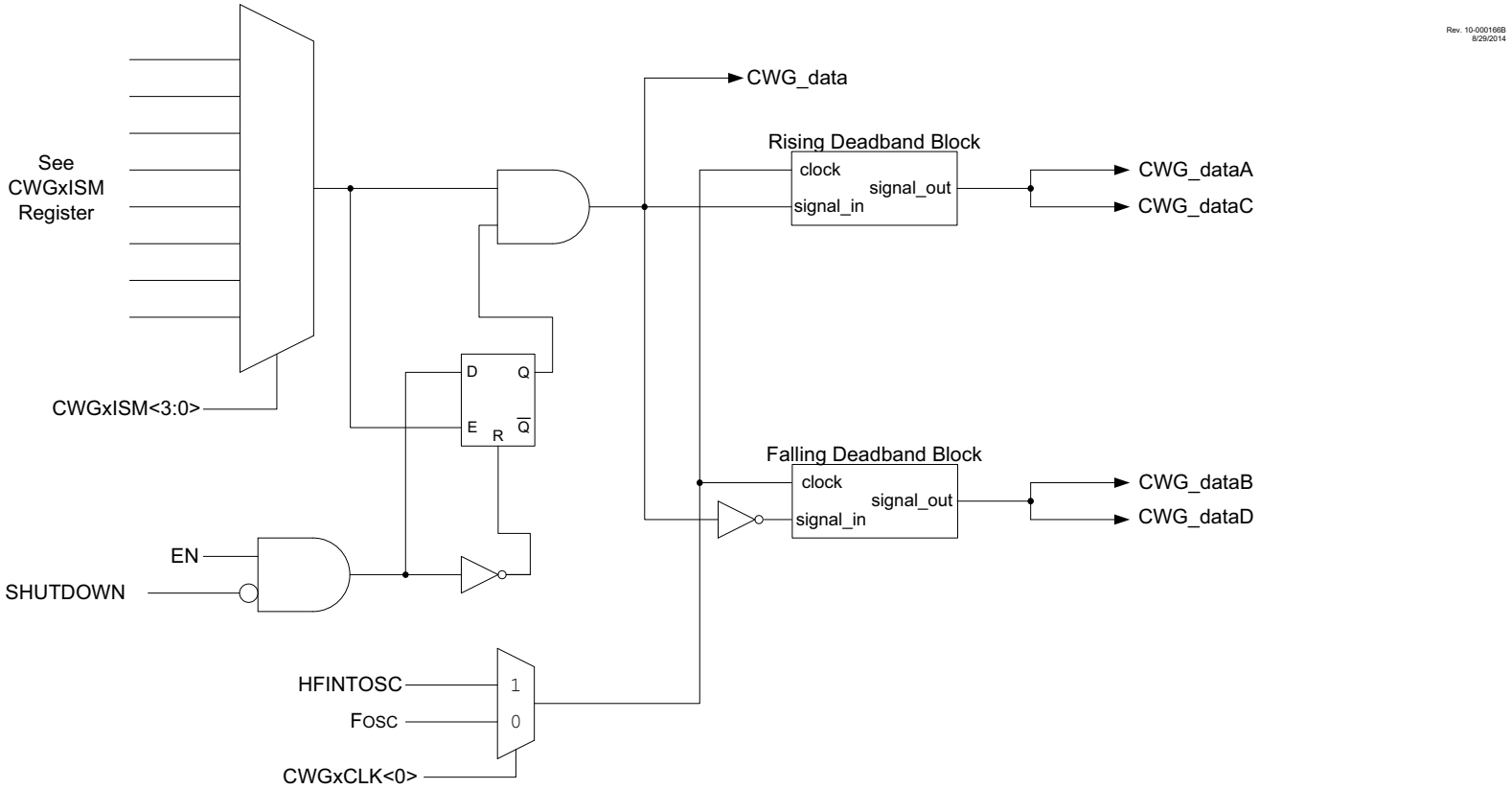


FIGURE 18-2: COMPARATOR MODULE SIMPLIFIED BLOCK DIAGRAM



Note 1: When CxON = 0, all multiplexer inputs are disconnected and the Comparator will produce a '0' at the output.

FIGURE 20-1: SIMPLIFIED CWG BLOCK DIAGRAM (HALF-BRIDGE MODE)



22.2 CLCx Interrupts

An interrupt will be generated upon a change in the output value of the CLCx when the appropriate interrupt enables are set. A rising edge detector and a falling edge detector are present in each CLC for this purpose.

The CLCxIF bit of the associated PIR5 register will be set when either edge detector is triggered and its associated enable bit is set. The LCxINTP enables rising edge interrupts and the LCxINTN bit enables falling edge interrupts. Both are located in the CLCxCON register.

To fully enable the interrupt, set the following bits:

- CLCxIE bit of the PIE5 register
- LCxINTP bit of the CLCxCON register (for a rising edge detection)
- LCxINTN bit of the CLCxCON register (for a falling edge detection)
- PEIE and GIE bits of the INTCON register

The CLCxIF bit of the PIR5 register, must be cleared in software as part of the interrupt service. If another edge is detected while this flag is being cleared, the flag will still be set at the end of the sequence.

22.3 Output Mirror Copies

Mirror copies of all LCxCON output bits are contained in the CLCxDATA register. Reading this register reads the outputs of all CLCs simultaneously. This prevents any reading skew introduced by testing or reading the LCxOUT bits in the individual CLCxCON registers.

22.4 Effects of a Reset

The CLCxCON register is cleared to zero as the result of a Reset. All other selection and gating values remain unchanged.

22.5 Operation During Sleep

The CLC module operates independently from the system clock and will continue to run during Sleep, provided that the input sources selected remain active.

The HFINTOSC remains active during Sleep when the CLC module is enabled and the HFINTOSC is selected as an input source, regardless of the system clock source selected.

In other words, if the HFINTOSC is simultaneously selected as the system clock and as a CLC input source, when the CLC is enabled, the CPU will go idle during Sleep, but the CLC will continue to operate and the HFINTOSC will remain active.

This will have a direct effect on the Sleep mode current.

22.6 CLCx Setup Steps

The following steps should be followed when setting up the CLCx:

- Disable CLCx by clearing the LCxEN bit.
- Select desired inputs using CLCxSEL0 through CLCxSEL3 registers (See Table 22-2).
- Clear any associated ANSEL bits.
- Set all TRIS bits associated with inputs.
- Clear all TRIS bits associated with outputs.
- Enable the chosen inputs through the four gates using CLCxGLS0, CLCxGLS1, CLCxGLS2, and CLCxGLS3 registers.
- Select the gate output polarities with the LCxGyPOL bits of the CLCxPOL register.
- Select the desired logic function with the LCxMODE<2:0> bits of the CLCxCON register.
- Select the desired polarity of the logic output with the LCxPOL bit of the CLCxPOL register. (This step may be combined with the previous gate output polarity step).
- If driving a device pin, set the desired pin PPS control register and also clear the TRIS bit corresponding to that output.
- If interrupts are desired, configure the following bits:
  - Set the LCxINTP bit in the CLCxCON register for rising event.
  - Set the LCxINTN bit in the CLCxCON register for falling event.
  - Set the CLCxIE bit of the PIE5 register.
  - Set the GIE and PEIE bits of the INTCON register.
- Enable the CLCx by setting the LCxEN bit of the CLCxCON register.

23.0 ANALOG-TO-DIGITAL CONVERTER WITH COMPUTATION (ADC^2) MODULE

The Analog-to-Digital Converter with Computation (ADC^2) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair).

Additionally, the following features are provided within the ADC module:

- 8-bit Acquisition Timer
- Hardware Capacitive Voltage Divider (CVD) support:
  - 8-bit Precharge Timer
  - Adjustable sample and hold capacitor array
  - Guard ring digital output drive
- Automatic repeat and sequencing:
  - Automated double sample conversion for CVD
  - Two sets of result registers (Result and Previous result)
  - Auto-conversion trigger
  - Internal retrigger
- Computation features:
  - Averaging and Low-Pass Filter functions
  - Reference Comparison
  - 2-level Threshold Comparison
  - Selectable Interrupts

Figure 23-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion and upon threshold comparison. These interrupts can be used to wake-up the device from Sleep.

TABLE 23-1: ADC CLOCK PERIOD (TAD) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (TAD)		Device Frequency (FOSC)					
ADC Clock Source	ADCCS<5:0>	32 MHz	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz
FOSC/2	000000	62.5ns(2)	100 ns(2)	125 ns(2)	250 ns(2)	500 ns(2)	2.0 μs
FOSC/4	000001	125 ns(2)	200 ns(2)	250 ns(2)	500 ns(2)	1.0 μs	4.0 μs
FOSC/6	000010	187.5 ns(2)	300 ns(2)	375 ns(2)	750 ns(2)	1.5 μs	6.0 μs
FOSC/8	000011	250 μs(2)	400 ns(2)	500 μs(2)	1.0 μs	2.0 μs	8.0 μs(3)
...	...	...	...	...	...	...	...
FOSC/16	000111	500 ns(2)	800 ns(2)	1.0 μs	2.0 μs	4.0 μs	16.0 μs(2)
...	...	...	...	...	...	...	...
FOSC/128	111111	4.0 μs	6.4 μs	8.0 μs	16.0 μs(3)	32.0 μs(2)	128.0 μs(2)
FRC	ADCS(ADCON0 <4>)=1	1.0-6.0 μs(1)	1.0-6.0 μs(1)	1.0-6.0 μs(1)	1.0-6.0 μs(1)	1.0-6.0 μs(1)	1.0-6.0 μs(1)

Legend: Shaded cells are outside of recommended range.

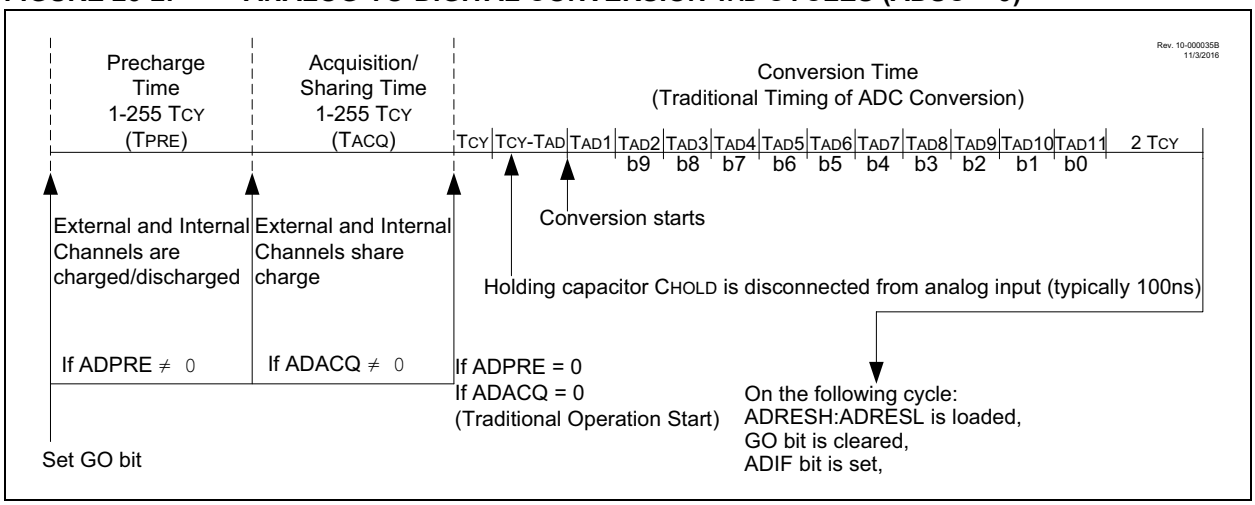
Note 1: See TAD parameter for FRC source typical TAD value.

2: These values violate the required TAD time.

3: Outside the recommended TAD time.

4: The ADC clock period (TAD) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock FOSC. However, the FRC oscillator source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 23-2: ANALOG-TO-DIGITAL CONVERSION TAD CYCLES (ADSC = 0)



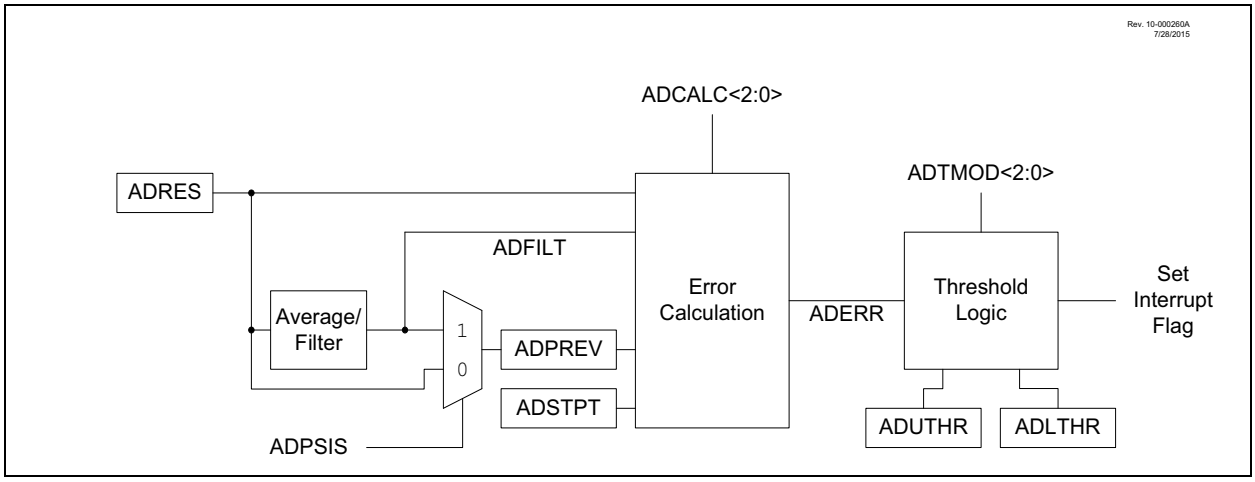
23.4.5 ADDITIONAL SAMPLE AND HOLD CAPACITANCE

Additional capacitance can be added in parallel with the internal sample and hold capacitor (CHOLD) by means of the ADCAP register. This register selects a digitally programmable capacitance which is added to the ADC conversion bus, increasing the effective internal capacitance of the sample and hold capacitor in the ADC module. This is used to improve the match between internal and external capacitance for a better sensing performance. The additional capacitance does not affect analog performance of the ADC because it is not connected during conversion. See Figure 23-10.

23.5 Computation Operation

The ADC module hardware is equipped with post conversion computation features. These features provide data post-processing functions that can be operated on the ADC conversion result, including digital filtering/averaging and threshold comparison functions.

FIGURE 23-10: COMPUTATIONAL FEATURES SIMPLIFIED BLOCK DIAGRAM



The operation of the ADC computational features is controlled by the ADMD <2:0> bits in the ADCON2 register.

The module can be operated in one of five modes:

• **Basic**: This is a legacy mode. In this mode, ADC conversion occurs on single (ADDSEN=0) or double (ADDSEN=1) samples. ADIF is set after each conversion completes.

• **Accumulate**: With each trigger, the ADC conversion result is added to accumulator and ADCNT increments. ADIF is set after each conversion. ADTIF is set according to the Calculation mode.

• **Average**: With each trigger, the ADC conversion result is added to the accumulator. When the ADRPT number of samples have been accumulated, a threshold test is performed. Upon the next trigger, the counter is reset to '1' and the accumulator is replaced with the first ADC conversion cleared. For the subsequent threshold tests, additional ADRPT samples are required to be accumulated.

• **Burst Average**: At the trigger, the accumulator and counter are cleared. The ADC conversion results are then collected repetitively until ADRPT samples are accumulated and finally the threshold is tested.

• **Low-Pass Filter (LPF)**: With each trigger, the ADC conversion result is sent through a filter. When ADRPT samples have occurred, a threshold test is performed. Every trigger after that the ADC conversion result is sent through the filter and another threshold test is performed.

The five modes are summarized in Table 23-3 below.

25.0 5-BIT DIGITAL-TO-ANALOG CONVERTER (DAC1) MODULE

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 32 selectable output levels.

The input of the DAC can be connected to:

- External VREF pins
- VDD supply voltage
- FVR (Fixed Voltage Reference)

The output of the DAC can be configured to supply a reference voltage to the following:

- Comparator positive input
- ADC input channel
- DAC1OUT pin

The Digital-to-Analog Converter (DAC) is enabled by setting the DAC1EN bit of the DAC1CON0 register.

25.1 Output Voltage Selection

The DAC has 32 voltage level ranges. The 32 levels are set with the DAC1R<4:0> bits of the DAC1CON1 register.

The DAC output voltage is determined by Equation 25-1:

EQUATION 25-1: DAC OUTPUT VOLTAGE

$$V_{OUT} = \left((V_{SOURCE+}) - (V_{SOURCE-}) \times \frac{DAC1R\langle 4:0 \rangle}{2^5} \right) + (V_{SOURCE-})$$

$$V_{SOURCE+} = V_{DD} \text{ or } V_{REF+} \text{ or } FVR$$

$$V_{SOURCE-} = V_{SS} \text{ or } V_{REF-}$$

25.2 Ratiometric Output Level

The DAC output value is derived using a resistor ladder with each end of the ladder tied to a positive and negative voltage reference input source. If the voltage of either input source fluctuates, a similar fluctuation will result in the DAC output value.

The value of the individual resistors within the ladder can be found in Table 37-15.

25.3 DAC Voltage Reference Output

The DAC voltage can be output to the DAC1OUT1/2 pins by setting the DAC1OE1/2 bits of the DAC1CON0 register, respectively. Selecting the DAC reference voltage for output on the DAC1OUT1/2 pins automatically overrides the digital output buffer and digital input threshold detector functions, disables the weak pull-up, and disables the current-controlled drive function of that pin. Reading the DAC1OUT1/2 pin when it has been configured for DAC reference voltage output will always return a '0'.

Due to the limited current drive capability, a buffer must be used on the DAC voltage reference output for external connections to the DAC1OUT1/2 pins. Figure 25-2 shows an example buffering technique.

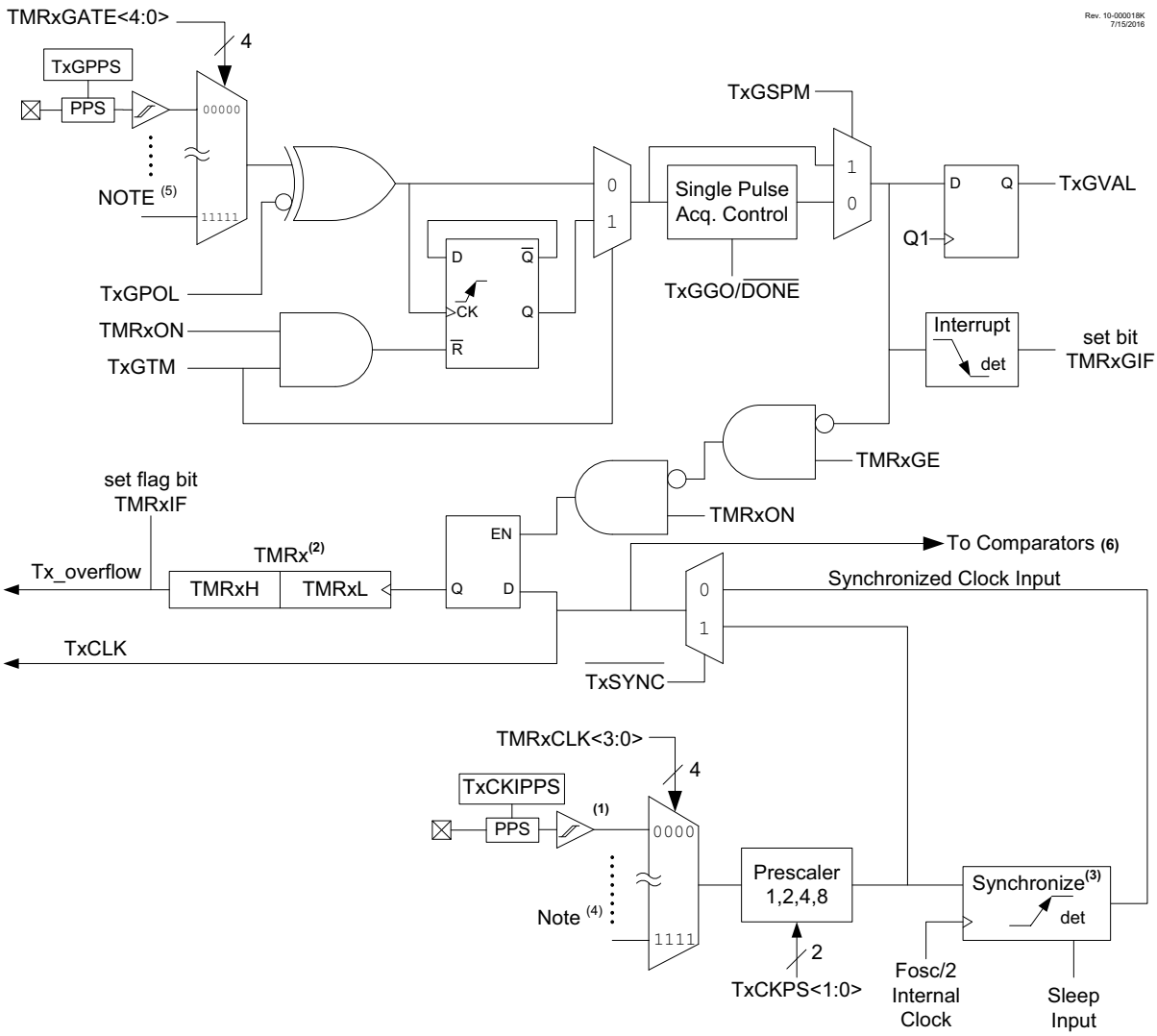
TABLE 27-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER0

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
TMR0L	Holding Register for the Least Significant Byte of the 16-bit TMR0 Register								404*
TMR0H	Holding Register for the Most Significant Byte of the 16-bit TMR0 Register								404*
T0CON0	T0EN	—	T0OUT	T016BIT	T0OUTPS<3:0>				407
T0CON1	T0CS<2:0>			T0ASYNC	T0CKPS<3:0>				408
T0CKIPPS	—	—	—	—	T0CKIPPS<3:0>				249
TMR0PPS	—	—	—	TMR0PPS<4:0>					249
ADACT	—	—	—	ADACT<4:0>					359
CLCxSELy	—	—	—	LCxDyS<4:0>					329
T1GCON	GE	GPOL	GTM	GSPM	GGO/$\overline{\text{DONE}}$	GVAL	—	—	420
INTCON	GIE	PEIE	—	—	—	—	—	INTEDG	134
PIR0	—	—	TMR0IF	IOCIF	—	—	—	INTF	144
PIE0	—	—	TMR0IE	IOCIE	—	—	—	INTE	135

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the Timer0 module.

* Page with Register information.

FIGURE 28-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is high speed type when using TxCKIPPS.
2: TMRx register increments on rising edge.
3: Synchronize does not operate while in Sleep.
4: See Register 28-3 for Clock source selections.
5: See Register 28-4 for GATE source selections.
6: Synchronized comparator output should not be used in conjunction with synchronized input clock.

30.3.4 TIMER2 TIMER RESOURCE

This device has a newer version of the TMR2 module that has many new modes, which allow for greater customization and control of the PWM signals than on older parts. Refer to Section 29.5, Operation Examples for examples of PWM signal generation using the different modes of Timer2. The CCP operation requires that the timer used as the PWM time base has the FOSC/4 clock source selected

30.3.5 PWM PERIOD

The PWM period is specified by the PR2/4/6 register of Timer2/4/6. The PWM period can be calculated using the formula of Equation 30-1.

EQUATION 30-1: PWM PERIOD

$$PWM\ Period = [(PR2) + 1] \bullet 4 \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

Note 1: TOSC = 1/FOSC

When TMR2/4/6 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2/4/6 is cleared
- The CCPx pin is set. (Exception: If the PWM duty cycle = 0%, the pin will not be set.)
- The PWM duty cycle is transferred from the CCPRxL/H register pair into a 10-bit buffer.

Note:	The Timer postscaler (see **Section 29.4 "Timer2 Interrupt"**) is not used in the determination of the PWM frequency.

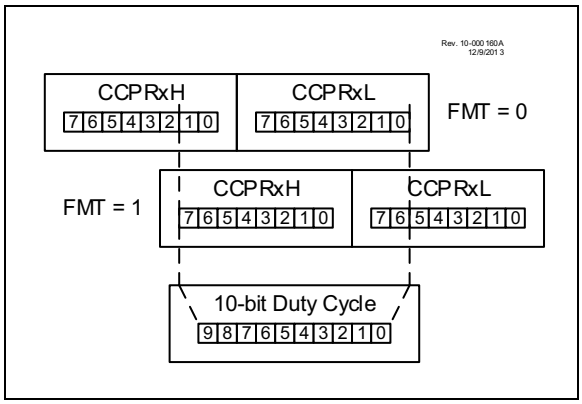
30.3.6 PWM DUTY CYCLE

The PWM duty cycle is specified by writing a 10-bit value to the CCPRxH:CCPRxL register pair. The alignment of the 10-bit value is determined by the CCPRxFMT bit of the CCPxCON register (see Figure 30-5). The CCPRxH:CCPRxL register pair can be written to at any time; however the duty cycle value is not latched into the 10-bit buffer until after a match between PR2 and TMR2.

Equation 30-2 is used to calculate the PWM pulse width.

Equation 30-3 is used to calculate the PWM duty cycle ratio.

FIGURE 30-5: PWM 10-BIT ALIGNMENT



EQUATION 30-2: PULSE WIDTH

$$Pulse\ Width = (CCPRxH{:}CCPRxL\ register\ pair) \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

EQUATION 30-3: DUTY CYCLE RATIO

$$Duty\ Cycle\ Ratio = \frac{(CCPRxH{:}CCPRxL\ register\ pair)}{4(PR2 + 1)}$$

CCPRxH:CCPRxL register pair are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

The 8-bit timer TMR2 register is concatenated with either the 2-bit internal system clock (FOSC), or two bits of the prescaler, to create the 10-bit time base. The system clock is used if the Timer2 prescaler is set to 1:1.

When the 10-bit time base matches the CCPRxH:CCPRxL register pair, then the CCPx pin is cleared (see Figure 30-4).

30.3.7 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is ten bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 30-4.

EQUATION 30-4: PWM RESOLUTION

$$Resolution = \frac{log[4(PR2 + 1)]}{log(2)}\ bits$$

Note:	If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

REGISTER 31-4: SSPxCON3: SSPx CONTROL REGISTER 3

R-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ACKTIM(3)	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ACKTIM:** Acknowledge Time Status bit (I^2C mode only)(3)
1 = Indicates the I^2C bus is in an Acknowledge sequence, set on 8th falling edge of SCL clock
0 = Not an Acknowledge sequence, cleared on 9TH rising edge of SCL clock

bit 6 **PCIE**: Stop Condition Interrupt Enable bit (I^2C Slave mode only)
1 = Enable interrupt on detection of Stop condition
0 = Stop detection interrupts are disabled(2)

bit 5 **SCIE**: Start Condition Interrupt Enable bit (I^2C Slave mode only)
1 = Enable interrupt on detection of Start or Restart conditions
0 = Start detection interrupts are disabled(2)

bit 4 **BOEN:** Buffer Overwrite Enable bit
In SPI Slave mode:(1)
1 = SSPxBUF updates every time that a new data byte is shifted in ignoring the BF bit
0 = If new byte is received with BF bit of the SSPxSTAT register already set, SSPOV bit of the SSPxCON1 register is set, and the buffer is not updated
In I^2C™ Master mode and SPI Master mode:
This bit is ignored.
In I^2C™ Slave mode:
1 = SSPxBUF is updated and $\overline{ACK}$ is generated for a received address/data byte, ignoring the state of the SSPOV bit only if the BF bit = 0.
0 = SSPxBUF is only updated when SSPOV is clear

bit 3 **SDAHT:** SDA Hold Time Selection bit (I^2C mode only)
1 = Minimum of 300 ns hold time on SDA after the falling edge of SCL
0 = Minimum of 100 ns hold time on SDA after the falling edge of SCL

bit 2 **SBCDE:** Slave Mode Bus Collision Detect Enable bit (I^2C Slave mode only)
If, on the rising edge of SCL, SDA is sampled low when the module is outputting a high state, the BCL1IF bit of the PIR3 register is set, and bus goes idle
1 = Enable slave bus collision interrupts
0 = Slave bus collision interrupts are disabled

bit 1 **AHEN:** Address Hold Enable bit (I^2C Slave mode only)
1 = Following the eighth falling edge of SCL for a matching received address byte; CKP bit of the SSPxCON1 register will be cleared and the SCL will be held low.
0 = Address holding is disabled

bit 0 **DHEN:** Data Hold Enable bit (I^2C Slave mode only)
1 = Following the eighth falling edge of SCL for a received data byte; slave hardware clears the CKP bit of the SSPxCON1 register and SCL is held low.
0 = Data holding is disabled

Note 1: For daisy-chained SPI operation; allows the user to ignore all but the last received byte. SSPOV is still set when a new byte is received and BF = 1, but hardware continues to write the most recent byte to SSPxBUF.
2: This bit has no effect in Slave modes that Start and Stop condition detection is explicitly listed as enabled.
3: The ACKTIM Status bit is only active when the AHEN bit or DHEN bit is set.

32.0 SIGNAL MEASUREMENT TIMER (SMT)

The SMT is a 24-bit counter with advanced clock and gating logic, which can be configured for measuring a variety of digital signal parameters such as pulse width, frequency and duty cycle, and the time difference between edges on two signals.

Features of the SMT include:

- 24-bit timer/counter
  - Three 8-bit registers (SMTxL/H/U)
  - Readable and writable
  - Optional 16-bit operating mode
- Two 24-bit measurement capture registers
- One 24-bit period match register
- Multi-mode operation, including relative timing measurement
- Interrupt on period match
- Multiple clock, gate and signal sources
- Interrupt on acquisition complete
- Ability to read current input values

Note:	These devices implement two SMT modules. All references to SMTx apply to SMT1 and SMT2.

33.4.2 SYNCHRONOUS SLAVE MODE

The following bits are used to configure the EUSART for synchronous slave operation:

- SYNC = 1
- CSRC = 0
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TX1STA register configures the device for synchronous operation. Clearing the CSRC bit of the TX1STA register configures the device as a slave. Clearing the SREN and CREN bits of the RC1STA register ensures that the device is in the Transmit mode, otherwise the device will be configured to receive. Setting the SPEN bit of the RC1STA register enables the EUSART.

33.4.2.1 EUSART Synchronous Slave Transmit

The operation of the Synchronous Master and Slave modes are identical (see **Section 33.4.1.3 "Synchronous Master Transmission")**, except in the case of the Sleep mode.

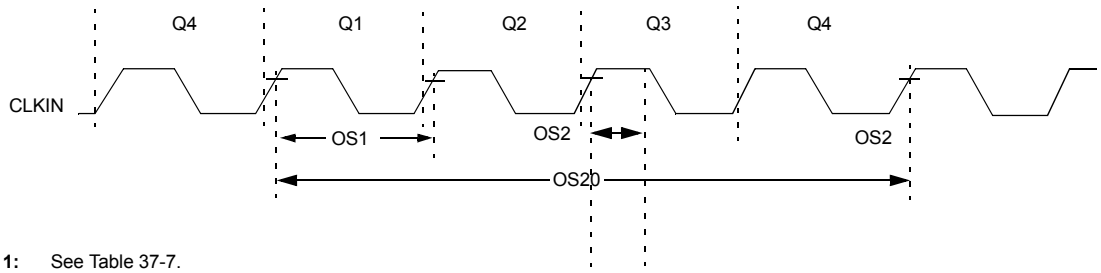
If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

1. The first character will immediately transfer to the TSR register and transmit.
2. The second word will remain in the TXREG register.
3. The TXIF bit will not be set.
4. After the first character has been shifted out of TSR, the TXREG register will transfer the second character to the TSR and the TXIF bit will now be set.
5. If the PEIE and TXIE bits are set, the interrupt will wake the device from Sleep and execute the next instruction. If the GIE bit is also set, the program will call the Interrupt Service Routine.

33.4.2.2 Synchronous Slave Transmission Set-up:

1. Set the SYNC and SPEN bits and clear the CSRC bit.
2. Clear the ANSEL bit for the CK pin (if applicable).
3. Clear the CREN and SREN bits.
4. If interrupts are desired, set the TXIE bit of the PIE3 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit transmission is desired, set the TX9 bit.
6. Enable transmission by setting the TXEN bit.
7. If 9-bit transmission is selected, insert the Most Significant bit into the TX9D bit.
8. Start transmission by writing the Least Significant eight bits to the TXREG register.

FIGURE 37-5: CLOCK TIMING



Note 1: See Table 37-7.

TABLE 37-7: EXTERNAL CLOCK/OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
ECL Oscillator							
OS1	F_{ECL}	Clock Frequency	—	—	500	kHz	
OS2	T_{ECL_DC}	Clock Duty Cycle	40	—	60	%	
ECM Oscillator							
OS3	F_{ECM}	Clock Frequency	—	—	8	MHz	
OS4	T_{ECM_DC}	Clock Duty Cycle	40	—	60	%	
ECH Oscillator							
OS5	F_{ECH}	Clock Frequency	—	—	32	MHz	
OS6	T_{ECH_DC}	Clock Duty Cycle	40	—	60	%	
LP Oscillator							
OS7	F_{LP}	Clock Frequency	—	—	100	kHz	**Note 4**
XT Oscillator							
OS8	F_{XT}	Clock Frequency	—	—	4	MHz	**Note 4**
HS Oscillator							
OS9	F_{HS}	Clock Frequency	—	—	20	MHz	**Note 4**
System Oscillator							
OS20	F_{OSC}	System Clock Frequency	—	—	32	MHz	**(Note 2, Note 3)**
OS21	F_{CY}	Instruction Frequency	—	FOSC/4	—	MHz	
OS22	T_{CY}	Instruction Period	125	$1/F_{CY}$	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: The system clock frequency (FOSC) is selected by the "main clock switch controls" as described in **Section 6.0 "Oscillator Module (with Fail-Safe Clock Monitor)"**.

3: The system clock frequency (FOSC) must meet the voltage requirements defined in the **Section 37.2 "Standard Operating Conditions"**.

4: LP, XT and HS oscillator modes require an appropriate crystal or resonator to be connected to the device. For clocking the device with the external square wave, one of the EC mode selections must be used.

Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

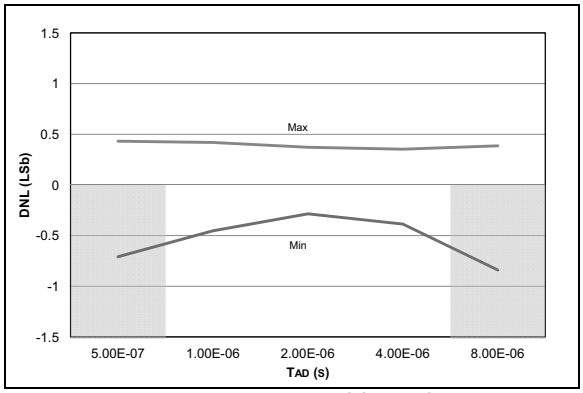


FIGURE 38-49: *ADC 10-bit Mode, Single-Ended DNL, VDD = 3.0V, VREF = 3.0V.*

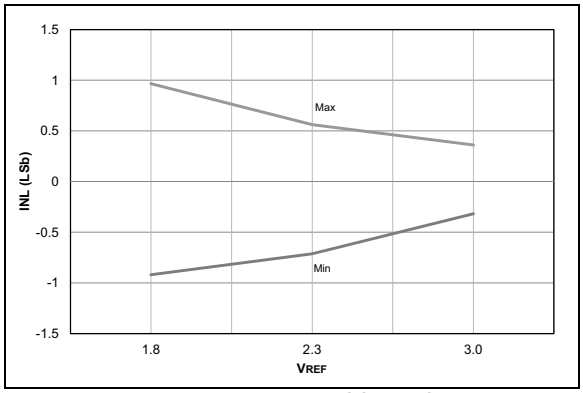


FIGURE 38-52: *ADC 10-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 1 µS.*

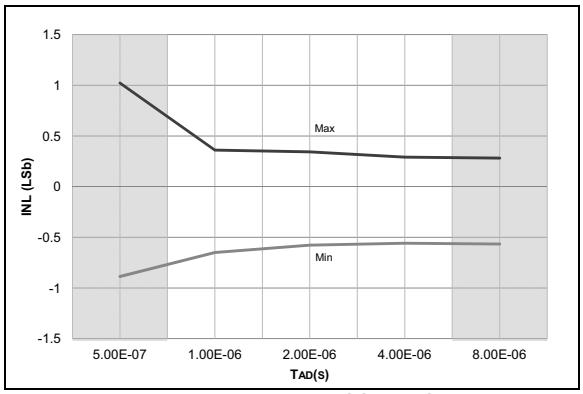


FIGURE 38-50: *ADC 10-bit Mode, Single-Ended INL, VDD = 3.0V, VREF = 3.0V.*

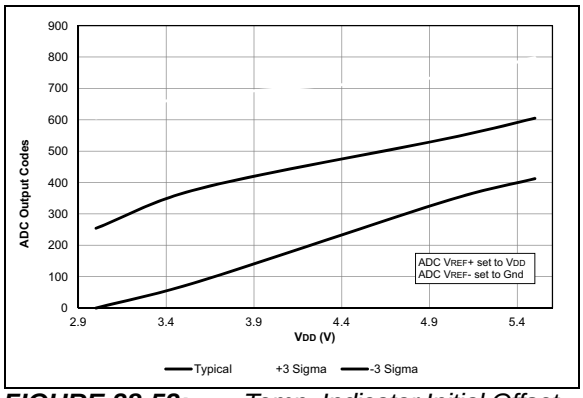


FIGURE 38-53: *Temp. Indicator Initial Offset, High Range, Temp. = 20°C, PIC16F18855/75 Only.*

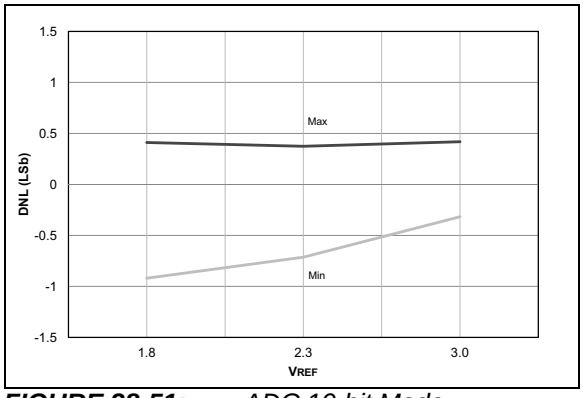


FIGURE 38-51: *ADC 10-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 1 µS.*

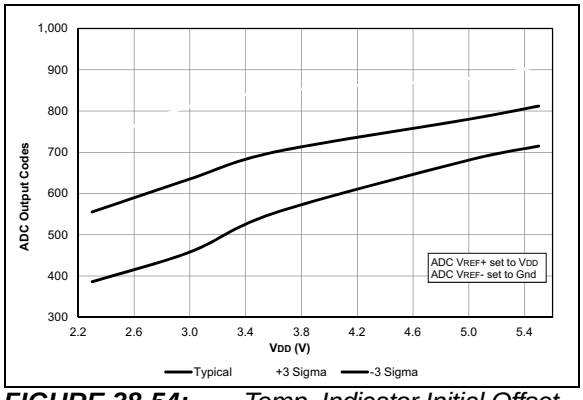


FIGURE 38-54: *Temp. Indicator Initial Offset, Low Range, Temp. = 20°C, PIC16F18855/75 Only.*